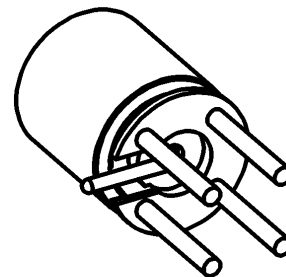
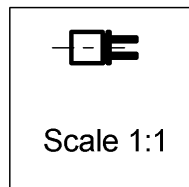
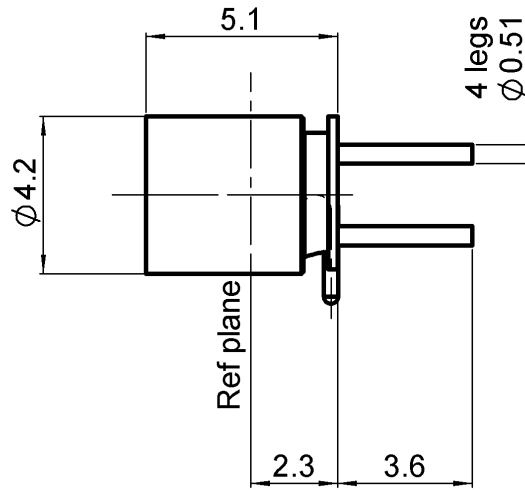
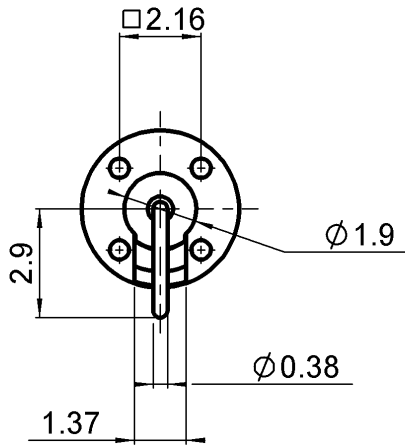
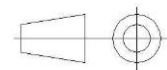


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All dimensions are in mm.



| COMPONENTS | MATERIALS | PLATING (µm) |
|----------------|--------------------------------|--|
| Body | STAINLESS STEEL + BRASS | PASSIVATED + GOLD 0.5 OVER NICKEL 2 |
| Center contact | BERYLLIUM COPPER | GOLD 1.27 OVER NICKEL 1.27 |
| Outer contact | | |
| Insulator | PTFE | |
| Gasket | | |
| Others parts | - | - |
| - | - | - |
| - | - | - |

| | | | |
|----------|------------------------|-------------------|-------------------------------|
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PACKAGING

| Standard | Unit | Other |
|------------|-------------------|-------------------|
| 100 | Contact us | Contact us |

ELECTRICAL CHARACTERISTICS

| | | | |
|---------------------------------|-----------------|---------------|-------------------|
| Impedance | | 50 | Ω |
| Frequency | | 0-40* | GHz |
| VSWR*** | 1.15** + | 0,0000 | x F(GHz) Maxi |
| Insertion loss | | 0.12* | √F(GHz) dB Maxi |
| RF leakage | - (| NA | - F(GHz)) dB Maxi |
| Voltage rating | | 335 | Veff Maxi |
| Dielectric withstanding voltage | | 500 | Veff mini |
| Insulation resistance | | 5000 | MΩ mini |

ENVIRONMENTAL

| | | |
|-----------------------|-----------------|-----------|
| Operating temperature | -65/+165 | °C |
| Hermetic seal | NA | Atm.cm3/s |
| Panel leakage | NA | |

MECHANICAL CHARACTERISTICS

| | | | |
|----------------------------|--|---------------|-------------|
| Center contact retention | | | |
| Axial force – Mating End | | 6.8 | N mini |
| Axial force – Opposite end | | 6.8 | N mini |
| Torque | | NA | N.cm mini |
| Recommended torque | | | |
| Mating | | NA | N.cm |
| Panel nut | | NA | N.cm |
| Mating life | | 500 | Cycles mini |
| Weight | | 0,3500 | g |

SPECIFICATION

OTHER CHARACTERISTICS

Assembly instruction:

Others:

Compliant with MIL-STD-348

***Coaxial transmission line only**

****DC-12.4 Ghz (Coaxial transmission line only)**

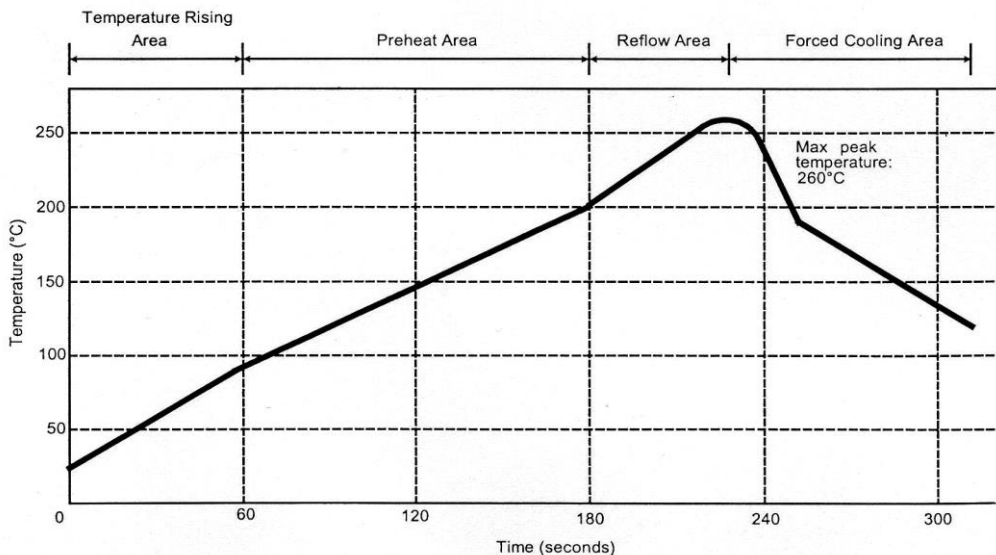
*****Performance strongly depends on layout and PCB material**

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SOLDER PROCEDURE

- Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
We advise a thickness of 150 microns (5.85 microinch). Verify that the edges of the zone are clean.
- Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
- Soldering by infra-red reflow.
Below, please find the typical profile to use.
- Cleaning of printed circuit boards.
- Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE

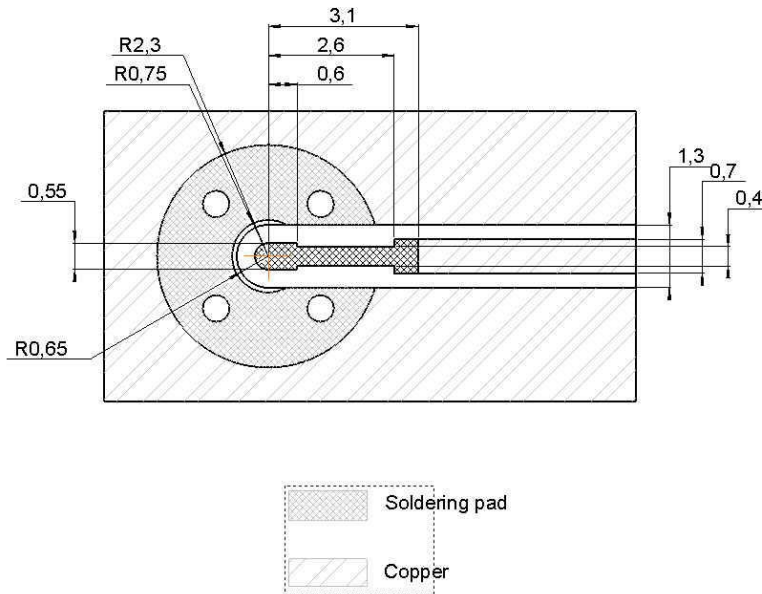


| Parameter | Value | Unit |
|----------------------------------|-----------|--------|
| Temperature rising Area | 1 - 4 | °C/sec |
| Max Peak Temperature | 260 | °C |
| Max dwell time @260°C | 10 | sec |
| Min dwell time @235°C | 20 | sec |
| Max dwell time @235°C | 60 | sec |
| Temperature drop in cooling Area | -1 to - 4 | °C/sec |
| Max dwell time above 100°C | 420 | sec |

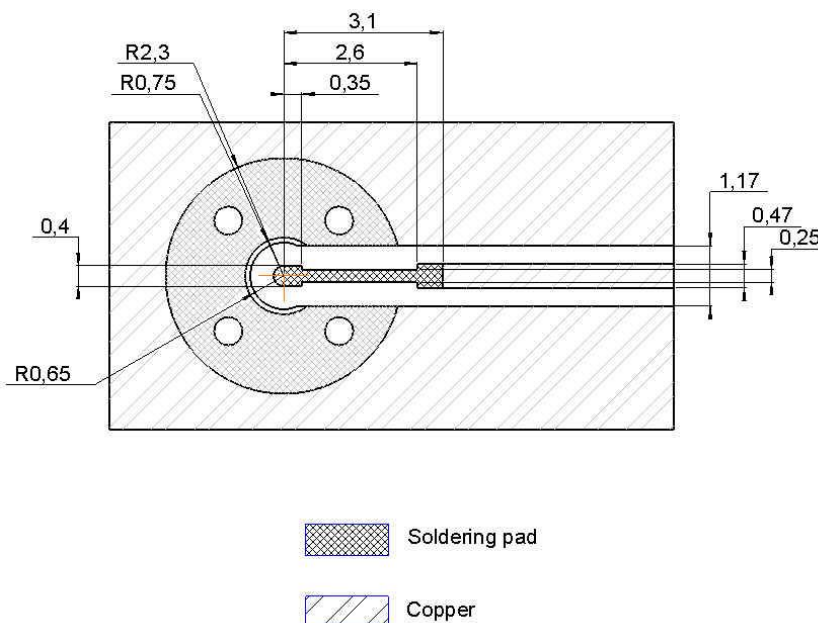
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RECOMMENDED PAD DIMENSIONS:

Substrate: RT5880 thickness 0.254mm, with copper layer 35µm on both sides :
Add vias between both sides along upper ground plane according to engineering practise



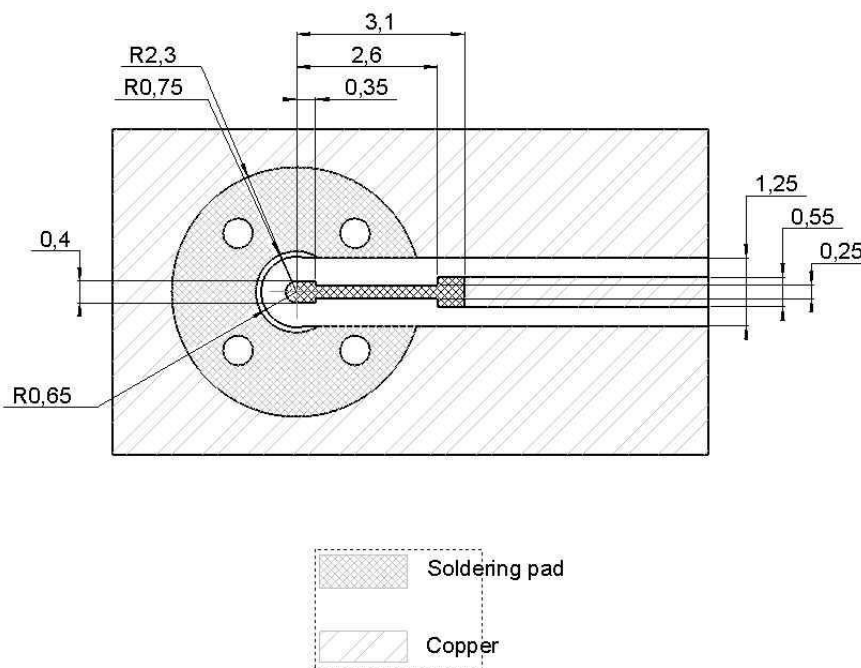
Substrate: RO4350 thickness 0.254mm, with copper layer 35µm on both sides :
Add vias between both sides along upper ground plane according to engineering practise



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Substrate: RO6002 thickness 0.254mm, with copper layer 35µm on both sides :

Add vias between both sides along upper ground plane according to engineering practise



SHADOW FOR VIDEO CAMERA

